# CMOS IC 8K-byte FROM and 256-byte RAM integrated 8-bit 1-chip Microcontroller



## Overview

The LC87FBH08A is an 8-bit microcontroller that, centered around a CPU running at a minimum bus cycle time of 83.3ns, integrates on a single chip a number of hardware features such as 8K-byte flash ROM (On-board-programmable), 256-byte RAM, an On-chip-debugger (flash versions only), sophisticated 16-bit timers/counters (may be divided into 8-bit timers), a 16-bit timer/counter (may be divided into 8-bit timers/counters or 8-bit PWMs), two 8-bit timers with a prescaler, a base timer serving as a time-of-day clock, a high-speed clock counter, a synchronous SIO interface, an asynchronous/synchronous SIO interface, a UART interface (full duplex), two 12-bit PWM channels, a 12-bit/8-bit 11-channel AD converter, a high-speed clock counter, a system clock frequency divider, an internal high-accuracy oscillator, a reference voltage generator circuit, an internal reset and a 20-source 10-vector interrupt feature.

## Features

#### ■Flash ROM

- Capable of On-board programming with wide range (2.2 to 5.5V) of voltage source.
- Block-erasable in 128 byte units
- Writable in 2-byte units
- 8192 × 8 bits

#### ■RAM

•  $256 \times 9$  bits

#### ■Minimum Bus Cycle

- 83.3ns (12MHz at VDD=2.7V to 5.5V, Ta=-40°C to +85°C)
- 100ns (10MHz at V<sub>DD</sub>=2.2V to 5.5V, Ta=-40°C to +85°C)
- 250ns (4MHz at V<sub>DD</sub>=1.8V to 5.5V, Ta=-40°C to +85°C) Note: The bus cycle time here refers to the ROM read speed.

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### ■Minimum Instruction Cycle Time

- 250ns (12MHz at V<sub>DD</sub>=2.7V to 5.5V, Ta=-40°C to +85°C)
- 300ns (10MHz at V<sub>DD</sub>=2.2V to 5.5V, Ta=-40°C to +85°C)
- 750ns (4MHz at VDD=1.8V to 5.5V, Ta=-40°C to +85°C)

#### ■Ports

- Normal withstand voltage I/O ports Ports I/O direction can be designated in 1-bit units Ports I/O direction can be designated in 4-bit units
- Dedicated oscillator ports/input ports
- Reset pin
- Power pins
- ■Timers
  - Timer 0: 16-bit timer/counter with a capture register.

17 (P1n, P20, P21, P30, P31, P70 to P73 CF2/XT2) 8 (P0n) 1 (CF1/XT1) 1 (RES) 3 (V<sub>SS</sub>1, V<sub>SS</sub>2, V<sub>DD</sub>1)

- Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register)  $\times$  2 channels Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register)
  - + 8-bit counter (with an 8-bit capture register)
  - Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)
- Mode 3: 16-bit counter (with a 16-bit capture register)
- Timer 1: 16-bit timer/counter that supports PWM/toggle outputs
  - Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + 8-bit timer/
    - counter with an 8-bit prescaler (with toggle outputs)
  - Mode 1: 8-bit PWM with an 8-bit prescaler  $\times$  2 channels
  - Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)
    - (toggle outputs also possible from the lower-order 8 bits)
  - Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)
    - (The lower-order 8 bits can be used as PWM)
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Base timer
  - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
  - 2) Interrupts are programmable in 5 different time schemes
- ■High-speed Clock Counter
  - Can count clocks with a maximum clock rate of 20MHz (at a main clock of 10MHz).
  - Can generate output real time.

#### ■SIO

- SIO0: 8-bit synchronous serial interface
  - 1) LSB first/MSB first mode selectable
  - 2) Built-in 8-bit baudrate generator (maximum transfer clock cycle =4/3 tCYC)
  - Automatic continuous data transmission (1 to 256 bits, specifiable in 1 bit units, suspension and resumption of data transmission possible in 1 byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
- Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks) Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates) Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
- Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)
- ∎UART1
  - Full duplex
  - 7/8/9 bit data bits selectable
  - 1 stop bit (2-bit in continuous data transmission)
  - Built-in baudrate generator

- AD converter: 12 bits/8 bits  $\times$  11 channels
  - Successive approximation
  - 12 bits/8 bits AD converter resolution selectable
  - Port input: 10 channels, Reference voltage input: 1 channel

■PWM: Multifrequency 12-bit PWM × 2 channels

■Reference voltage generator circuit (VREF17)

• Capable of monitoring the power supply voltage by AD conversion of frequency variable RC oscillator circuit's reference voltage.

■Remote Control Receiver Circuit (sharing pins with P73, INT3, and T0IN)

• Noise rejection function (noise filter time constant selectable from 1 tCYC, 32 tCYC, and 128 tCYC)

Clock Output Function

- Capable generating clock outputs with a frequency of 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, 1/64 of the source clock selected as the system clock.
- Capable of generating the source clock for the subclock.

#### ■Watchdog Timer

- Capable of generating an internal reset on an overflow of a timer running on the low-speed RC oscillator clock or subclock.
- Operating mode at standby is selectable from 3 modes (continue counting/stop operation/stop counting with a count value held).

#### ■Interrupts

- 20 sources, 10 vector addresses
  - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
  - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INTO
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	тон
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/UART1 receive
8	0003BH	H or L	SIO1/UART1 transmit
9	00043H	H or L	ADC/T6/T7/ PWM4, PWM5
10	0004BH	H or L	Port 0

• Priority levels X > H > L

• Of interrupts of the same level, the one with the smallest vector address takes precedence.

Subroutine Stack Levels: 128levels (The stack is allocated in RAM.)

#### ■High-speed Multiplication/Division Instructions

- 16 bits  $\times$  8 bits (5 tCYC execution time)
- 24 bits  $\times$  16 bits (12 tCYC execution time)
- 16 bits ÷ 8 bits (8 tCYC execution time)
- 24 bits  $\div$  16 bits (12 tCYC execution time)

## ■Oscillation Circuits

- Internal oscillation circuits
- Low-speed RC oscillation circuit (SRC):For system clock / For Watchdog timer (100kHz)Medium-speed RC oscillation circuit (RC):For system clock (1MHz)Frequency variable RC oscillation circuit (MRC):For system clock (8MHz ± 1.5%, Ta=-10°C to +85°C)• External oscillation circuits
- Hi-speed CF oscillation circuit (CF):
   For system clock, with internal Rf

   Low speed crystal oscillation circuit (X'tal):
   For low-speed system clock / For Watchdog timer, with internal Rf
  - The CF and crystal oscillation circuits share the same pins. The active circuit is selected under program control.
     Both the CF and crystal oscillator circuits stop operation on a system reset. After reset is released, oscillation is stopped so start the oscillation operation by program.

## System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2µs, 2.4µs, 4.8µs, 9.6µs, 19.2µs, 38.4µs, and 76.8µs (at a main clock rate of 10MHz).
- ■Internal Reset Function
  - Power-on reset (POR) function
    - 1) POR reset is generated only at power-on time.
    - 2) The POR release level can be selected from 8 levels (1.67V, 1.97V, 2.07V, 2.37V, 2.57V, 2.87V, 3.86V, and 4.35V) through option configuration.
  - Low-voltage detection reset (LVD) function
  - 1) LVD and POR functions are combined to generate resets when power is turned on and when power voltage falls below a certain level.
  - 2) The use or disuse of the LVD function and the low voltage threshold level (7 levels: 1.91V, 2.01V, 2.31V, 2.51V, 2.81V, 3.79V, 4.28V) can be selected by optional configuration.

## ■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
  - 1) Oscillation is not halted automatically.
  - 2) There are four ways of resetting the HALT mode.
    - (1) Setting the reset pin to the low level
    - (2) System resetting by low-voltage detection
    - (3) System resetting by watchdog timer
    - (4) Occurrence of an interrupt
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
  - The CF, low-/medium-/ Frequency variable RC, and crystal oscillators automatically stop operation. Note: The oscillation of the low-speed RC oscillator is also controlled directly by the watchdog timer and its standby-mode-time oscillation is also controlled.
  - 2) There are five ways of resetting the HOLD mode.
    - (1) Setting the reset pin to the lower level.
    - (2) System resetting by low-voltage detection
    - (3) System resetting by watchdog timer
    - (4) Having an interrupt source established at either INT0, INT1, INT2, INT4, INT5
      - \* INT0 and INT1 HOLD mode reset is available only when level detection is set.
    - (5) Having an interrupt source established at port 0.

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- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer. 1) The CF, low-/medium-/ Frequency variable RC oscillators automatically stop operation.
  - Note: The oscillation of the low-speed RC oscillator is also controlled directly by the watchdog timer and its standby-mode-time oscillation is also controlled.
  - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
  - 3) There are six ways of resetting the X'tal HOLD mode.
    - (1) Setting the reset pin to the low level.
    - (2) System resetting by watchdog timer or low-voltage detection.
    - (3) System resetting by watchdog timer or low-voltage detection.
    - (4) Having an interrupt source established at either INT0, INT1, INT2, INT4, INT5 \* INT0 and INT1 HOLD mode reset is available only when level detection is set.
    - (5) Having an interrupt source established at port 0.
    - (6) Having an interrupt source established in the base timer circuit. Note: Available only when X'tal oscillation is selected.

■Onchip Debugger (flash versions only)

- Supports software debugging with the microcontroller mounted on the target board.
- Software break setting
- Stepwise execution of instructions
- Real time RAM data monitoring function All the RAM data map contents can be monitored and rewritten on the screen when the program is running. (Part of the SFR data cannot be rewritten.)
- Two channels of on-chip debugger pins are available to be compatible with small pin count devices. DBGP0 (P0), DBGP1 (P1)

Data Security Function (flash versions only)

• Protects the program data stored in flash memory from unauthorized read or copy. Note: This data security function does not necessarily provide absolute data security.

■Package Form

- QFP36(7mm×7mm): Lead-/Halogen-free type
- VQLP32(4mm×4mm): Lead-/Halogen-free type (build-to-order)

■Development Tools

- On-chip-debugger : (1) TCB87 TypeB + LC87FBH08A
  - (2) TCB87 TypeC (3 wire version) + LC87FBH08A

■Flash ROM Programming Boards

Package	Programming boards
QFP36 (7mm×7mm)	W87F24Q
VQLP32 (4mm×4mm)	(build-to-order)

Maker		Model	Supported version	Device
	Single Programmer	AF9709/AF9709B/AF9709C (Including Ando Electric Co., Ltd. models)	Rev 03.28 or later	87F008SU
Flash Support Group, Inc. (FSG)	Gang	AF9723/AF9723B(Main body) (Including Ando Electric Co., Ltd. models)	-	-
	Programmer	AF9833(Unit) (Including Ando Electric Co., Ltd. models)	-	-
Flash Support Group, Inc. (FSG)	In-circuit	AF9101/AF9103(Main body) (FSG models)		
+ Our company (Note 1)	Programmer	SIB87(Inter Face Driver) (Our company model)	(Note 2)	-
Our company	Single/Gang Programmer	SKK / SKK Type B / SKK Type C (SanyoFWS)	Application Version 1.07 or later	
	In-circuit/Gang Programmer	SKK-DBG Type B / SKK-DBG Type C (SanyoFWS)	Chip Data Version 2.38 or later	LC87FBH08

For information about AF-Series:

Flash Support Group, Inc.

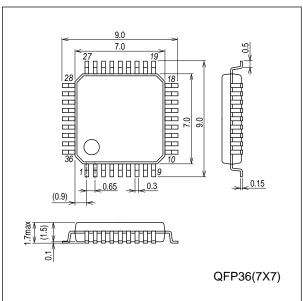
TEL: +81-53-459-1050

E-mail: sales@j-fsg.co.jp

- Note1: On-board-programmer from FSG (AF9101/AF9103) and serial interface driver from Our company (SIB87) together can give a PC-less, standalone on-board-programming capabilities.
- Note2: It needs a special programming devices and applications depending on the use of programming environment. Please ask FSG or Our company for the information.

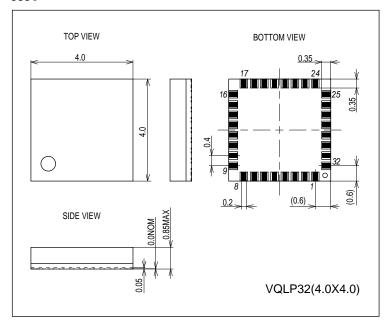
# Package Dimensions

unit : mm (typ) 3162C

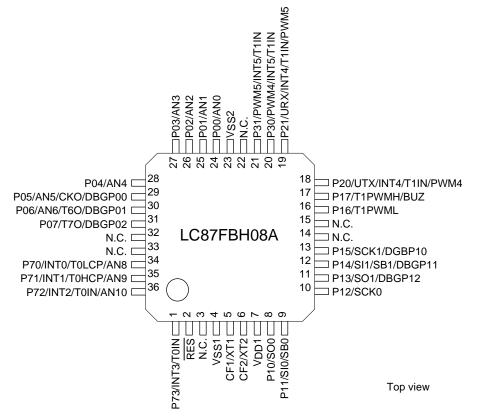


# Package Dimensions

unit : mm (typ) 3331



## **Pin Assignment**

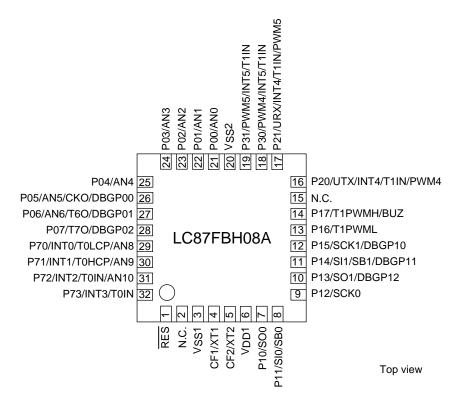


QFP36 (7mm×7mm) "Lead-/Halogen-free Type"

QFP36	NAME
1	P73/INT3/T0IN
2	RES
3	N.C.
4	V <sub>SS</sub> 1
5	CF1/XT1
6	CF2/XT2
7	V <sub>DD</sub> 1
8	P10/SO0
9	P11/SI0/SB0
10	P12/SCK0
11	P13/SO1/DBGP12
12	P14/SI1/SB1/DBGP11
13	P15/SCK1/DBGP10
14	N.C.
15	N.C.
16	P16/T1PWML
17	P17/T1PWMH/BUZ
18	P20/UTX/INT4/T1IN/PWM4

QFP36	NAME
19	P21/URX/INT4/T1IN/PWM5
20	P30/PWM4/INT5/T1IN
21	P31/PWM5/INT5/T1IN
22	N.C.
23	V <sub>SS</sub> 2
24	P00/AN0
25	P01/AN1
26	P02/AN2
27	P03/AN3
28	P04/AN4
29	P05/AN5/CKO/DBGP00
30	P06/AN6/T6O/DBGP01
31	P07/T7O/DBGP02
32	N.C.
33	N.C.
34	P70/INT0/T0LCP/AN8
35	P71/INT1/T0HCP/AN9
36	P72/INT2/T0IN/AN10

Note: N.C. pins must be held open (disconnected).

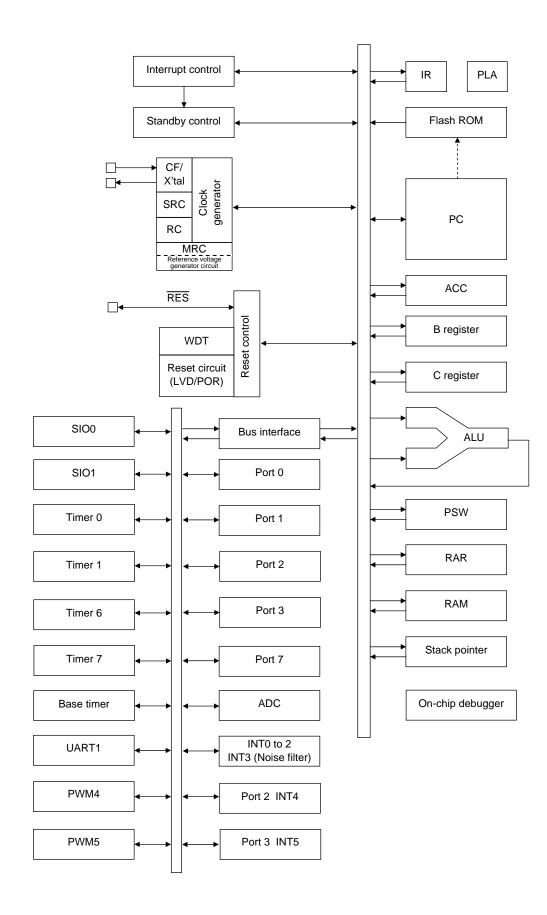


VQLP32 (4mm×4mm) "Lead-/Halogen-free Type" (build-to-order )

VQLP32	NAME	VQLP32	NAME
1	RES	17	P21/URX/INT4/T1IN/PWM5
2	N.C.	18	P30/PWM4/INT5/T1IN
3	V <sub>SS</sub> 1	19	P31/PWM5/INT5/T1IN
4	CF1/XT1	20	V <sub>SS</sub> 2
5	CF2/XT2	21	P00/AN0
6	V <sub>DD</sub> 1	22	P01/AN1
7	P10/SO0	23	P02/AN2
8	P11/SI0/SB0	24	P03/AN3
9	P12/SCK0	25	P04/AN4
10	P13/SO1/DBGP12	26	P05/AN5/CKO/DBGP00
11	P14/SI1/SB1/DBGP11	27	P06/AN6/T6O/DBGP01
12	P15/SCK1/DBGP10	28	P07/T7O/DBGP02
13	P16/T1PWML	29	P70/INT0/T0LCP/AN8
14	P17/T1PWMH/BUZ	30	P71/INT1/T0HCP/AN9
15	N.C.	31	P72/INT2/T0IN/AN10
16	P20/UTX/INT4/T1IN/PWM4	32	P73/INT3/T0IN

Note: N.C. pins must be held open (disconnected).

# System Block Diagram



# **Pin Function Chart**

Pin Name	I/O			Des	scription			Option	
V <sub>SS</sub> 1, V <sub>SS</sub> 2	-	- Power supply	pin					No	
V <sub>DD</sub> 1	-	+ Power supply	, pin					No	
Port 0	I/O	8-bit I/O port							
P00 to P07	_	<ul> <li>I/O specifiable</li> </ul>	e in 4-bit units						
		Pull-up resisto	ors can be turned	on and off in 4	-bit units.				
		HOLD reset in	nput						
		Port 0 interrup	ot input						
		Pin functions						Yes	
		P05: System of	clock output						
		P06: Timer 6 t	toggle output						
		P07: Timer 7 1	toggle output						
		P00(AN0) to F	P06(AN6): AD cor	nverter input					
			) to P07(DBGP02	2): On-chip debu	ugger 0 port				
Port 1	I/O	<ul> <li>8-bit I/O port</li> </ul>							
P10 to P17		<ul> <li>I/O specifiable</li> </ul>							
		•	ors can be turned	l on and off in 1	-bit units.				
		Pin functions							
		P10: SIO0 dat	-						
		P11: SIO0 dat P12: SIO0 clo	ta input/bus I/O						
		P12: SIO0 clo P13: SIO1 dat						Yes	
			ta input / bus I/O						
		P15: SIO1 clo	-						
		P16: Timer 1F							
			PWMH output / be	eeper output					
			) to P13(DBGP12		ugger 1 port				
Port 2	I/O	• 2-bit I/O port							
P20 to P21		<ul> <li>I/O specifiable</li> </ul>	e in 1-bit units						
		<ul> <li>Pull-up resistor</li> </ul>	ors can be turned	l on and off in 1	-bit units.				
		<ul> <li>Pin functions</li> </ul>							
		P20: UART tra	ansmit / PWM4 o	utput					
			ceive / PWM5 ou	•					
		P20 to P21: INT4 input / HOLD reset input / timer 1 event input / timer 0L capture input /							
			mer 0H capture i	nput					
		Interrupt ackn	owledge types		Disian 8				
			Rising	Falling	Rising & Falling	H level	L level		
		INT4	anabla	anabla	enable	diaabla	diaphla		
		IN14	enable	enable	enable	disable	disable		
Port 3	I/O	• 2-bit I/O port							
P30 to P31		<ul> <li>I/O specifiable</li> </ul>	e in 1 bit units						
		Pull-up resisto	ors can be turned	on and off in 1	bit units.				
		Pin functions							
		P30: PWM4 o	output						
		P31: PWM5 o	output						
		P30 to P31: I	NT5 input/HOLD	reset input / tim	er 1 event input	/ timer 0L captu	re input /	Yes	
		t	imer 0H capture i	input					
		Interrupt ackn	owledge types		1	1	· · · · · ·		
			Rising	Falling	Rising &	H level	L level		
					Falling				
		INT5		enable	enable	disable	disable		

Continued on next page.

Pin Name	I/O			Des	cription			Option		
Port 7	I/O	<ul> <li>4-bit I/O port</li> </ul>								
P70 to P73		<ul> <li>I/O specifiable</li> </ul>	<ul> <li>I/O specifiable in 1 bit units</li> </ul>							
		Pull-up resisto								
		• Pin functions								
		P70: INT0 inp	ut / HOLD reset	input / timer 0L	capture input					
		P71: INT1 inp	ut / HOLD reset	input / timer 0H	capture input					
		P72: INT2 inp	ut / HOLD reset	input / timer 0 e	vent input / timer	0L capture inp	ut			
		P73: INT3 inp								
		P70(AN8) to P72(AN10): AD converter input								
		Interrupt acknowledge types								
			Rising	Falling	Rising &	H level	L level			
			Kisilig	r ann y	Falling	TTIEvei	Lievei			
		INT0	enable	enable	disable	enable	enable			
		INT1	enable	enable	disable	enable	enable			
		INT2	enable	enable	enable	disable	disable			
		INT3	enable	enable	enable	disable	disable			
RES	1/0									
	I/O	External reset in						No		
CF1/XT1	I	Ceramic resor	ator or 32.768kl	Iz crystal oscilla	tor input pin					
		<ul> <li>Pin function</li> </ul>						No		
	General-purpose input port									
CF2/XT2	I/O	Ceramic resor	ator or 32.768k	Iz crystal oscilla	tor output pin					
		<ul> <li>Pin function</li> </ul>						No		
		General-purpo	se I/O port							

# **Port Output Types**

The table below lists the types of port outputs and the presence/absence of a pull-up resistor. Data can be read into any input port even if it is in the output mode.

Port Name	Option selected in units of	Option type	Output type	Pull-up resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P21	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P30 to P31	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
CF2/XT2	-	No	Ceramic resonator/32.768kHz crystal resonator output Nch-open drain (N-channel open drain when set to general-purpose	No
			output port)	

Note 1: The control of the presence or absence of the programmable pull-up resistors for port 0 and the switching between low-and high-impedance pull-up connection is exercised in nibble (4-bit) units (P00 to 03 or P04 to 07).

## **User Option Table**

Option Name	Option to be Applied on	Mask version *1	Flash-ROM Version	Option Selected in Units of	Option Selection
Port output type	P00 to P07	0	0	1 bit	CMOS
					Nch-open drain
	P10 to P17	0	0	1 bit	CMOS
					Nch-open drain
	P20 to P21	0	0	1 bit	CMOS
					Nch-open drain
	P30 to P31	0	0	1 bit	CMOS
					Nch-open drain
Program start	-	×	0	-	00000h
address		*2			01E00h
Low-voltage	Detect function	0	0	-	Enable:Use
detection reset					Disable:Not Used
function	Detect level	0	0	-	7-level
Power-on reset function	Power-On reset level	0	0	-	8-level

\*1: Mask option selection - No change possible after mask is completed.

\*2: Program start address of the mask version is 00000h.

## **Recommended Unused Pin Connections**

Deat Name	Recommended Unused Pin Connections		
Port Name	Board	Software	
P00 to P07	Open	Output low	
P10 to P17	Open	Output low	
P20 to P21	Open	Output low	
P30 to P31	Open	Output low	
P70 to P73	Open	Output low	
CF1/XT1	Pulled low with a 100k $\Omega$ resistor or less	General-purpose input port	
CF2/XT2	Pulled low with a $100k\Omega$ resistor or less	General-purpose input port	

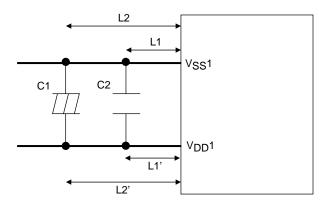
## **On-chip Debugger Pin Connection Requirements**

For the treatment of the on-chip debugger pins, refer to the separately available documents entitled "RD87 on-chip debugger installation manual".

## Power Pin Treatment Recommendations (VDD1, VSS1)

Connect bypass capacitors that meet the following conditions between the VDD1 and VSS1 pins:

- Connect among the V<sub>DD</sub>1 and V<sub>SS</sub>1 pins and bypass capacitors C1 and C2 with the shortest possible heavy lead wires, making sure that the impedances between the both pins and the bypass capacitors are as possible (L1=L1', L2=L2').
- Connect a large-capacity capacitor C1 and a small-capacity capacitor C2 in parallel. The capacitance of C2 should approximately 0.1µF.



Note: Be sure to electrically short-circuit between the VSS1 and VSS2 pins.

	Deremeter	Cumbal	Din/Domorko	Conditions			Specif	ication	
	Parameter	Symbol Pin/Remarks		Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
	ximum supply tage	V <sub>DD</sub> max	V <sub>DD</sub> 1			-0.3		+6.5	
Input voltage		VI	CF1			-0.3		V <sub>DD</sub> +0.3	v
Input/output voltage		V <sub>IO</sub>	Ports 0, 1, 2, 3, Port 7, CF2, RES			-0.3		V <sub>DD</sub> +0.3	
ent	Peak output current	IOPH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-10			
curre		IOPH(2)	P71 to P73	Per 1 applicable pin		-5			
High level output current	Mean output current	IOMH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-7.5			
evel	(Note 1-1)	IOMH(2)	P71 to P73	Per 1 applicable pin		-3			
High le	Total output current	ΣIOAH(1)	Ports 0, 1, 2, 3, P71 to P73	Total of all applicable pins		-25			
	Peak output current	IOPL(1)	P02 to P07, Ports 1, 2, 3	Per 1 applicable pin				20	mA
¥		IOPL(2)	P00, P01	Per 1 applicable pin				30	
urrer		IOPL(3)	Port 7, CF2	Per 1 applicable pin				10	
Low level output current	Mean output current	IOML(1)	P02 to P07 Ports 1, 2, 3	Per 1 applicable pin				15	
velo	(Note 1-1)	IOML(2)	P00, P01	Per 1 applicable pin				20	
w le		IOML(3)	Port 7, CF2	Per 1 applicable pin				7.5	1
ΓC	Total output current	ΣIOAL(1)	Ports 0, 1, Ports 2, 3, CF2	Total of all applicable pins				70	
		ΣIOAL(2)	Port 7	Total of all applicable pins				15	
Pov dise	wer sipation	Pd max(1)	QFP36(7×7)	Ta=-40 to +85°C Package only				120	
		Pd max(2)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				275	mV
	erating ambient	Topr				-40		+85	
	orage ambient	Tstg				-55		+125	°C

## Absolute Maximum Ratings at $Ta = 25^{\circ}C$ , $V_{SS}1 = V_{SS}2 = 0V$

Note 1-1: The mean output current is a mean value measured over 100ms.

Note 1-2: SEMI standards thermal resistance board (size: 76.1×114.3×1.6tmm, glass epoxy) is used.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Parameter	Symbol	Pin/Remarks	Conditions		<u>├</u>		fication	1
	-			V <sub>DD</sub> [V]	min	typ	max	uni
Operating	V <sub>DD</sub> (1)	V <sub>DD</sub> 1	0.245μs ≤ tCYC ≤ 200μs		2.7		5.5	
supply voltage (Note 2-1)	V <sub>DD</sub> (2)	_	0.294µs ≤ tCYC ≤ 200µs		2.2		5.5	
	V <sub>DD</sub> (3)		0.735µs ≤ tCYC ≤ 200µs		1.8		5.5	
Memory sustaining supply voltage	VHD	V <sub>DD</sub> 1	RAM and register contents sustained in HOLD mode.		1.6			
High level	V <sub>IH</sub> (1)	Ports 1, 2, 3, 7		1.8 to 5.5	0.3V <sub>DD</sub> +0.7		V <sub>DD</sub>	
input voltage	V <sub>IH</sub> (2)	Ports 0		1.8 to 5.5	0.3V <sub>DD</sub> +0.7		V <sub>DD</sub>	V
	V <sub>IH</sub> (3)	CF1, CF2, RES		1.8 to 5.5	0.75V <sub>DD</sub>		V <sub>DD</sub>	
Low level	V <sub>IL</sub> (1)	Ports 1, 2, 3, 7		4.0 to 5.5	VSS		0.1V <sub>DD</sub> +0.4	
input voltage				1.8 to 4.0	VSS		0.2V <sub>DD</sub>	
	V <sub>IL</sub> (2)	Ports 0		4.0 to 5.5	VSS		0.15V <sub>DD</sub> +0.4	
				1.8 to 4.0	V <sub>SS</sub>		0.2V <sub>DD</sub>	
	V <sub>IL</sub> (3)	CF1, CF2, RES		1.8 to 5.5	V <sub>SS</sub>		0.25V <sub>DD</sub>	
High level	I <sub>OH</sub> (1)	Ports 0, 1, 2,	Per 1 applicable pin	4.5 to 5.5	-1.0			
output current	I <sub>OH</sub> (2)	P71 to P73		2.7 to 4.5	-0.35			]
	I <sub>OH</sub> (3)	]		1.8 to 2.7	-0.15			]
	I <sub>OH</sub> (4)	Ports 3, P05 (System clock	Per 1 applicable pin	4.5 to 5.5	-6.0			
	I <sub>OH</sub> (5)	output function		2.7 to 4.5	-1.4			
	I <sub>OH</sub> (6)	used)		1.8 to 2.7	-0.8			
	$\Sigma^{I}OH^{(1)}$	Ports 0, 1, 2, 3, 7	Total of all applicable pins	4.5 to 5.5	-25			
	$\Sigma I_{OH}(2)$			2.7 to 4.5	-11.2			
	∑l <sub>OH</sub> (3)			1.8 to 2.7	-5.4			
Low level	I <sub>OL</sub> (1)	Ports 0, 1, 2, 3	Per 1 applicable pin	4.5 to 5.5			10	
output current	I <sub>OL</sub> (2)			2.7 to 4.5			1.4	mA
	I <sub>OL</sub> (3)			1.8 to 2.7			0.8	
	I <sub>OL</sub> (4)	Port 7, CF2	Per 1 applicable pin	2.7 to 5.5			1.4	
	I <sub>OL</sub> (5)	-		1.8 to 2.7			0.8	
	I <sub>OL</sub> (6)	P00, P01	Per 1 applicable pin	4.5 to 5.5			25	
	I <sub>OL</sub> (7)			2.7 to 4.5			4	
	I <sub>OL</sub> (8)	-		1.8 to 2.7			2	
	$\Sigma I_{OL}(1)$	Ports 0, 1, 2, 3,	Total of all applicable pins	4.5 to 5.5			70	1
	$\Sigma I_{OL}(2)$	CF2		2.7 to 4.5			34.6	
	$\Sigma I_{OL}(3)$	-		1.8 to 2.7			19.2	
	$\Sigma I_{OL}(4)$	Ports 7	Total of all applicable pins	2.7 to 5.5	+		5.6	1
	$\Sigma I_{OL}(5)$	-		1.8 to 2.7			3.2	1
Instruction	tCYC			2.7 to 5.5	0.245		200	-
cycle time				2.7 to 5.5	0.243		200	μs
(Note 2-2)					0.294		200	μο
External	FEXCF	CF1	• CF2 pin open	1.8 to 5.5 2.7 to 5.5	0.735		12	
system clock frequency			<ul> <li>System clock frequency division ratio=1/1</li> </ul>					-
			External system clock duty=50±5%     CF2 pin open	1.8 to 5.5	0.1		4	мн
			System clock frequency division     ratio=1/2	3.0 to 5.5	0.2		24.4	-
			External system clock duty=50±5%	2.0 to 5.5	0.2		8	

Note 2-1: V<sub>DD</sub> must be held greater than or equal to 2.2V in the flash ROM onboard programming mode. Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Continued on next page.

<b>D</b>		Pin/Remarks			Specification				
Parameter	Symbol		Conditions	V <sub>DD</sub> [V]	min	typ	max	unit	
Oscillation frequency	FmCF(1)         CF1, CF2         12MHz ceramic oscillation.           See Fig. 1.         See Fig. 1.		2.7 to 5.5		12				
range (Note 2-3)	FmCF(2)	CF1, CF2	F2 10MHz ceramic oscillation. 2 See Fig. 1. 2			10			
	FmCF(3)	CF1, CF2	4MHz ceramic oscillation. CF oscillation normal amplifier size selected. (CFLAMP=0) See Fig. 1.	1.8 to 5.5		4			
			4MHz ceramic oscillation. CF oscillation low amplifier size selected. (CFLAMP=1) See Fig. 1.	2.2 to 5.5		4		MHz	
	FmMRC(1)		Frequency variable RC oscillation. (Note 2-4)	1.8 to 5.5	7.84	8.0	8.16		
	FmMRC(2)		Frequency variable RC oscillation. • Ta=-10 to +85°C (Note 2-4)	1.8 to 5.5	7.88	8.0	8.12		
	FmRC		Internal medium-speed RC oscillation	1.8 to 5.5	0.5	1.0	2.0		
	FmSRC		Internal low-speed RC oscillation	1.8 to 5.5	50	100	200		
	FsX'tal	FsX'tal XT1, XT2 32.768kHz crystal oscillation See Fig. 1.		1.8 to 5.5		32.768		kHz	
Oscillation stabilization time	tmsMRC		When Frequency variable RC oscillation state is switched from stopped to enabled. See Fig. 3.	1.8 to 5.5			100	μs	

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Note 2-4: When switching the system clock, allow an oscillation stabilization time of 100µs or longer after the frequency variable RC oscillator circuit transmits from the "oscillation stopped" to "oscillation enabled" state.

Parameter	Symbol	Pin/Remarks	Conditions			Specifica	tion		
i alametei	Gymbol	T III/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit	
High level input current	I <sub>IH</sub> (1)	Ports 0, 1, 2, 3, Ports 7, RES	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	1.8 to 5.5			1		
	I <sub>IH</sub> (2)	CF1, CF2	Input port selected VIN=VDD	1.8 to 5.5			1		
	IIH(3)	CF1	F1 Reset state V <sub>IN</sub> =V <sub>DD</sub>				15	μA	
Low level input current	I <sub>IL</sub> (1)	Ports 0, 1, 2, 3, Ports 7, RES	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	1.8 to 5.5	-1				
	I <sub>IL</sub> (2)	CF1, CF2	Input port selected VIN=VSS	1.8 to 5.5	-1				
High level output	V <sub>OH</sub> (1)	Ports 0, 1, 2	I <sub>OH</sub> =-1mA	4.5 to 5.5	V <sub>DD</sub> -1				
voltage	V <sub>OH</sub> (2)	P71 to P73	I <sub>OH</sub> =-0.35mA	2.7 to 5.5	V <sub>DD</sub> -0.4				
	V <sub>OH</sub> (3)		I <sub>OH</sub> =-0.15mA	1.8 to 5.5	V <sub>DD</sub> -0.4				
	V <sub>OH</sub> (4)	Ports 3	I <sub>OH</sub> =-6mA	4.5 to 5.5	V <sub>DD</sub> -1				
	V <sub>OH</sub> (5)	P05 (System clock output	I <sub>OH</sub> =-1.4mA	2.7 to 5.5	V <sub>DD</sub> -0.4				
	V <sub>OH</sub> (6)	function used)	I <sub>OH</sub> =-0.8mA	1.8 to 5.5	V <sub>DD</sub> -0.4				
Low level output	V <sub>OL</sub> (1)	Ports 0, 1, 2, 3	I <sub>OL</sub> =10mA	4.5 to 5.5			1.5	v	
voltage	V <sub>OL</sub> (2)		I <sub>OL</sub> =1.4mA	2.7 to 5.5			0.4		
	V <sub>OL</sub> (3)		I <sub>OL</sub> =0.8mA	1.8 to 5.5			0.4		
	V <sub>OL</sub> (4)	Port 7, CF2	I <sub>OL</sub> =1.4mA	2.7 to 5.5			0.4		
	V <sub>OL</sub> (5)		I <sub>OL</sub> =0.8mA	1.8 to 5.5			0.4		
	V <sub>OL</sub> (6)	P00, P01	I <sub>OL</sub> =25mA	4.5 to 5.5			1.5		
	V <sub>OL</sub> (7)		I <sub>OL</sub> =4mA	2.7 to 5.5			0.4		
	V <sub>OL</sub> (8)		I <sub>OL</sub> =2mA	1.8 to 5.5			0.4		
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3,	V <sub>OH</sub> =0.9V <sub>DD</sub>	4.5 to 5.5	15	35	80		
	Rpu(2)	Ports 7	When Port 0 selected low-impedance pull-up.	1.8 to 4.5	18	50	230		
	Rpu(3)	Port 0	V <sub>OH</sub> =0.9V <sub>DD</sub> When Port 0 selected high-impedance pull-up.	1.8 to 5.5	100	200	400	kΩ	
Hysteresis voltage	VHYS(1)	Ports 1, 2, 3,		2.7 to 5.5		0.1V <sub>DD</sub>			
-	VHYS(2)	Ports 7, RES		1.8 to 2.7				V	
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	1.8 to 5.5		10		pF	

		Doromotor	Cumb al	Pin/	Conditions			Spec	ification	
	ł	Parameter	Symbol	Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
		Frequency	tSCK(1)	SCK0(P12)	See Fig. 5.		2			
		Low level pulse width	tSCKL(1)				1			
	Input clock	High level pulse width	tSCKH(1)			1.8 to 5.5	1			tCYC
il clock	ial clock		tSCKHA(1)		Continuous data transmission/reception mode     See Fig. 5. (Note 4-1-2)		4			τυγυ
Seria		Frequency	tSCK(2)	SCK0(P12)	CMOS output selected		4/3			
	Output clock	Low level pulse width	tSCKL(2)		• See Fig. 5.			1/2		tSCK
		High level	tSCKH(2)			1.8 to 5.5		1/2		
	Outpr	pulse width	tSCKHA(2)		<ul> <li>Continuous data transmission/reception mode</li> <li>CMOS output selected</li> <li>See Fig. 5.</li> </ul>		tSCKH(2) +2tCYC		tSCKH(2) +(10/3) tCYC	tCYC
input	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	Must be specified with     respect to rising edge of		0.05			
Serial input	Da	ta hold time	thDI(1)		SIOCLK. • See Fig. 5.	1.8 to 5.5	0.05			
	Input clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transmission/reception mode (Note 4-1-3)				(1/3)tCYC +0.08	
output	Serial output Output clock Input		tdD0(2)		Synchronous 8-bit mode (Note 4-1-3)	1.8 to 5.5			1tCYC +0.08	μs
Seria			tdD0(3)		(Note 4-1-3)				(1/3)tCYC +0.08	

## **SIO0 Serial I/O Characteristics** at $Ta = -40^{\circ}C$ to $+85^{\circ}C$ , $V_{SS}1 = V_{SS}2 = 0V$ (Note 4-1-1)

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: To use serial-clock-input in continuous trans/rec mode, a time from SIORUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 5.

## SIO1 Serial I/O Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$ , $V_{SS}1 = V_{SS}2 = 0V$ (Note 4-2-1)

		Doromotor	Cumphiel	Pin/	Conditions			Speci	fication	
	1	Parameter	Symbol	Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
		Frequency	tSCK(3)	SCK1(P15)	• See Fig. 5.		2			
	Input clock	Low level pulse width	tSCKL(3)			1.8 to 5.5	1			tCYC
Serial clock	High level pulse width	tSCKH(3)				1			tCYC	
erial	×	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected		2			
S	8	Low level pulse width	tSCKL(4)		• See Fig. 5.	1.8 to 5.5	1/2			tSCK
	Output	High level pulse width	tSCKH(4)					1/2		ISON
Serial input	Data setup time		tsDI(2)	SI1(P14), SB1(P14)	<ul> <li>Must be specified with respect to rising edge of</li> </ul>	4.045.5.5	(1/3)tCYC +0.01			
Serial	Da	ta hold time	thDI(2)		SIOCLK. • See Fig. 5.	1.8 to 5.5	0.01			
Serial output	Οι	itput delay time	tdD0(4)	SO1(P13), SB1(P14)	<ul> <li>Must be specified with respect to falling edge of SIOCLK.</li> <li>Must be specified as the time to the beginning of output state change in open drain output mode.</li> <li>See Fig. 5.</li> </ul>	1.8 to 5.5			(1/2)tCYC +0.05	μs

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

Pulse Input Conditions at Ta = $-40^{\circ}$ C to $+85^{\circ}$ C, V <sub>SS</sub> 1 = V <sub>SS</sub> 2 = 0V

Devenueter	Symbol	Pin/Remarks	O an althic ma		Specification				
Parameter		Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit	
High/low level pulse width	tPIH(1) tPIL(1)	INT0(P70), INT1(P71), INT2(P72), INT4(P20 to P21) INT5(P30 to P31)	<ul> <li>Interrupt source flag can be set.</li> <li>Event inputs for timer 0 or 1 are enabled.</li> </ul>	1.8 to 5.5	1				
	tPIH(2) tPIL(2)	INT3(P73) when noise filter time constant is 1/1	<ul> <li>Interrupt source flag can be set.</li> <li>Event inputs for timer 0 are enabled.</li> </ul>	1.8 to 5.5	2			tCYC	
	tPIH(3) tPIL(3)	INT3(P73) when noise filter time constant is 1/32	<ul> <li>Interrupt source flag can be set.</li> <li>Event inputs for timer 0 are nabled.</li> </ul>	1.8 to 5.5	64				
	tPIH(4) tPIL(4)	INT3(P73) when noise filter time constant is 1/128	<ul> <li>Interrupt source flag can be set.</li> <li>Event inputs for timer 0 are enabled.</li> </ul>	1.8 to 5.5	256				
	tPIL(5)	RES	<ul> <li>Resetting is enabled.</li> </ul>	1.8 to 5.5	200			μs	

## AD Converter Characteristics at $V_{SS}1 = V_{SS}2 = 0V$

<12bits AD Converter Mode/Ta =  $-40^{\circ}$ C to  $+85^{\circ}$ C >

Damandan	O maked	Pin/Remarks	Oraditions	_		Specifi	cation	
Parameter	Symbol		Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Resolution	Ν	AN0(P00) to		1.8 to 5.5		12		bit
Absolute	ET	AN6(P06),	(Note 6-1)	2.7 to 5.5			±16	1.05
accuracy		AN8(P70) to AN10(P72)		1.8 to 5.5			±20	LSB
Conversion time T	TCAD	TCAD	See Conversion time calculation formulas. (Note 6-2)	2.7 to 5.5	32		115	
				2.2 to 5.5	134		215	μs
				1.8 to 5.5	400		430	
Analog input voltage range	VAIN			1.8 to 5.5	V <sub>SS</sub>		V <sub>DD</sub>	V
Analog port	IAINH		VAIN=V <sub>DD</sub>	1.8 to 5.5			1	
input current	IAINL	]	VAIN=V <sub>SS</sub>	1.8 to 5.5	-1			μA

<8bits AD Converter Mode/Ta = -40°C to +85°C >

Deverseter	O: make al	Pin/Remarks	Oraditions		Specification				
Parameter	Symbol		Conditions	V <sub>DD</sub> [V]	min	typ	max	unit	
Resolution	N	AN0(P00) to		1.8 to 5.5		8		bit	
Absolute accuracy	ET	AN6(P06), AN8(P70) to	(Note 6-1)	1.8 to 5.5			±1.5	LSB	
Conversion time	TCAD	AN10(P72)	See Conversion time calculation	2.7 to 5.5	20		90		
			formulas. (Note 6-2)	2.2 to 5.5	80		135	μs	
				1.8 to 5.5	245		265		
Analog input voltage range	VAIN			1.8 to 5.5	V <sub>SS</sub>		V <sub>DD</sub>	V	
Analog port	IAINH		VAIN=V <sub>DD</sub>	1.8 to 5.5			1		
input current IAINL	1	VAIN=V <sub>SS</sub>	1.8 to 5.5	-1			μA		

Note 6-1: The quantization error (±1/2LSB) must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.

Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

Conversion time calculation formulas:

12bits AD Converter Mode: TCAD(Conversion time) =  $((52/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$ 8bits AD Converter Mode: TCAD(Conversion time) =  $((32/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$ 

External oscillation	Operating supply voltage range	System division ratio	Cycle time (tCYC)	AD division ratio	AD conversion time (TCAD)		
(FmCF)	(V <sub>DD</sub> )	(SYSDIV)	(tCYC)	(ADDIV)	12bit AD	8bit AD	
CF-12MHz	2.7V to 5.5V	1/1	250ns	1/8	34.8μs	21.5µs	
05 01 11	2.7V to 5.5V	1/1	375ns	1/8	52.25µs	32.25µs	
CF-8MHz	2.2V to 5.5V	1/1	375ns	1/32	208.25µs	128.25µs	
CF-4MHz	2.7V to 5.5V	1/1	750ns	1/8	104.5µs	64.5µs	
	2.2V to 5.5V	1/1	750ns	1/16	208.5µs	128.5µs	
	1.8V to 5.5V	1/1	750ns	1/32	416.5µs	256.5µs	

## **Reference voltage (VREF17) Characteristics** at $Ta = -40^{\circ}C$ to $+85^{\circ}C$ , $V_{SS}1 = V_{SS}2 = 0V$

Devenueter	Symbol Din/Domorko		O an dition o			Specific	ation	
Parameter	Symbol	Pin/Remarks Conditions VDD[V]		V <sub>DD</sub> [V]	min	typ	max	unit
Output voltage	VOVREF			2.0 to 5.5	1.67	1.75	1.83	V
Reference voltage operation current (Note 7-1)	IDDVREF			2.0 to 5.5		110		μΑ
Operation stabilization time (Note 7-2)	tVRW			2.0 to 5.5			100	μs

Note 7-1: IDDVREF denotes the currents that only flow to multivariable RC oscillator circuit's reference voltage circuit. Note 7-2: tVRW denotes the stabilization time from starting multivariable RC oscillator.

## **Power-on Reset (POR) Characteristics** at $Ta = -40^{\circ}C$ to $+85^{\circ}C$ , $V_{SS}1 = V_{SS}2 = 0V$

						Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min	typ	max	unit
POR release	PORRL		Select from option.	1.67V	1.55	1.66	1.77	
voltage			(Note 8-1)	1.97V	1.85	1.96	2.07	
				2.07V	1.93	2.05	2.17	
				2.37V	2.23	2.35	2.47	
				2.57V	2.43	2.55	2.67	V
				2.87V	2.71	2.85	2.99	v
				3.86V	3.65	3.83	4.00	
				4.35V	4.12	4.32	4.50	
Detection voltage unknown state	POUKS		• See Fig. 7. (Note 8-2)			0.7	0.95	
Power supply rise time	PORIS		<ul> <li>Power supply rise time from 0V to 1.6V.</li> </ul>				100	ms

Note8-1: The POR release level can be selected out of 8 levels only when the LVD reset function is disabled. Note8-2: POR is in an unknown state before transistors start operation.

## Low Voltage Detection Reset (LVD) Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = 0V$

						Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min	typ	max	unit
LVD reset voltage	LVDET		<ul> <li>Select from option.</li> </ul>	1.91V	1.81	1.91	2.01	
(Note 9-2)			(Note 9-1)	2.01V	1.90	2.00	2.10	
			(Note 9-3)	2.31V	2.20	2.30	2.40	
			See Fig. 8.	2.51V	2.40	2.50	2.60	V
				2.81V	2.68	2.80	2.92	
				3.79V	3.62	3.78	3.94	
				4.28V	4.09	4.27	4.45	
LVD hysteresis width	LVHYS			1.91V		50		
				2.01V		50		
				2.31V		50		
				2.51V		50		mV
				2.81V		50		
				3.79V		50		
				4.28V		50		
Detection voltage unknown state	LVUKS		<ul> <li>See Fig. 8.</li> <li>(Note 9-4)</li> </ul>			0.7	0.95	V
Low voltage detection minimum width (Reply sensitivity)	TLVDW		• LVDET-0.5V • See Fig. 9.		0.2			ms

Note9-1: The LVD reset level can be selected out of 7 levels only when the LVD reset function is enabled.

Note9-2: LVD reset voltage specification values do not include hysteresis voltage.

Note9-3: LVD reset voltage may exceed its specification values when port output state changes and/or when a large current flows through port.

Note9-4: LVD is in an unknown state before transistors start operation.

## Consumption Current Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = 0V$

Parameter	Symbol	Pin/	Conditions			Specif	ication	1
	Cymbol	Remarks		V <sub>DD</sub> [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V <sub>DD</sub> 1	FmCF=12MHz ceramic oscillation mode     System clock set to 12MHz side     Internal low speed and medium speed RC	2.7 to 5.5		5.1	9.3	
(Note 10-1) (Note 10-2)			<ul> <li>oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/1 frequency division ratio</li> </ul>	2.7 to 3.6		3.1	5.6	
	IDDOP(2)		<ul> <li>CF1=24MHz external clock</li> <li>System clock set to CF1 side</li> <li>Internal low speed and medium speed RC</li> </ul>	3.0 to 5.5		5.2	10	
			oscillation stopped. <ul> <li>Frequency variable RC oscillation stopped.</li> <li>1/2 frequency division ratio</li> </ul>	3.0 to 3.6		3.3	6.2	
	IDDOP(3)		<ul> <li>FmCF=10MHz ceramic oscillation mode</li> <li>System clock set to 10MHz side</li> <li>Internal low speed and medium speed RC</li> </ul>	2.2 to 5.5		4.4	8.4	
			oscillation stopped. <ul> <li>Frequency variable RC oscillation stopped.</li> <li>1/1 frequency division ratio</li> </ul>	2.2 to 3.6		2.8	5.5	
	IDDOP(4)		<ul> <li>FmCF=4MHz ceramic oscillation mode</li> <li>System clock set to 4MHz side</li> <li>Internal low speed and medium speed RC</li> </ul>	1.8 to 5.5		2.3	5.3	
			oscillation stopped. <ul> <li>Frequency variable RC oscillation stopped.</li> <li>1/1 frequency division ratio</li> </ul>	1.8 to 3.6		1.6	3.0	mA
	IDDOP(5)		<ul> <li>CF oscillation low amplifier size selected. (CFLAMP=1)</li> <li>FmCF=4MHz ceramic oscillation mode</li> <li>System clock set to 4MHz side</li> </ul>	2.2 to 5.5		0.97	2.4	
			<ul> <li>Internal low speed and medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/4 frequency division ratio</li> </ul>	2.2 to 3.6		0.55	1.2	
	IDDOP(6)		<ul> <li>FsX'tal=32.768kHz crystal oscillation mode</li> <li>Internal low speed RC oscillation stopped.</li> <li>System clock set to internal medium speed</li> </ul>	1.8 to 5.5		0.44	1.5	
			RC oscillation. • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	1.8 to 3.6		0.28	0.80	
	IDDOP(7)		<ul> <li>FsX'tal=32.768kHz crystal oscillation mode</li> <li>Internal low speed and medium speed RC oscillation stopped.</li> </ul>	1.8 to 5.5		3.4	5.5	
			<ul> <li>System clock set to 8MHz with frequency variable RC oscillation</li> <li>1/1 frequency division ratio</li> </ul>	1.8 to 3.6		2.4	4.6	
	IDDOP(8)		<ul> <li>External FsX'tal and FmCF oscillation stopped.</li> <li>System clock set to internal low speed RC oscillation.</li> </ul>	1.8 to 5.5		51	163	
			<ul> <li>Internal medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/1 frequency division ratio</li> </ul>	1.8 to 3.6		38	103	
	IDDOP(9)		<ul> <li>External FsX'tal and FmCF oscillation stopped.</li> <li>System clock set to internal low speed RC oscillation.</li> </ul>	5.0		51	136	μA
			<ul> <li>Internal medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/1 frequency division ratio</li> </ul>	3.3		38	99	
			• Ta=-10 to +50°C	2.5		36	94	

Note10-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note10-2: The consumption current values do not include operational current of LVD function if not specified.

Continued on next page.

Parameter	Symbol	Pin/	Conditions			Specif	ication	
Parameter	Symbol	Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(10)	V <sub>DD</sub> 1	<ul> <li>FsX'tal=32.768kHz crystal oscillation mode</li> <li>System clock set to 32.768kHz side</li> <li>Internal low speed and medium speed RC</li> </ul>	1.8 to 5.5		34	97	
(Note 10-1) (Note 10-2)			<ul> <li>oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/2 frequency division ratio</li> </ul>	1.8 to 3.6		14	44	
	IDDOP(11)		<ul> <li>FsX'tal=32.768kHz crystal oscillation mode</li> <li>System clock set to 32.768kHz side</li> <li>Internal low speed and medium speed RC</li> </ul>	5.0		34	88	μA
			<ul> <li>Internal low speed and medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> </ul>	3.3		14	36	
		-	1/2 frequency division ratio     Ta=-10 to +50°C	2.5		9.1	22	
HALT mode consumption current (Note 10-1)	IDDHALT(1)		<ul> <li>HALT mode</li> <li>FmCF=12MHz ceramic oscillation mode</li> <li>System clock set to 12MHz side</li> <li>Internal low speed and medium speed RC</li> </ul>	2.7 to 5.5		2.6	4.8	
(Note 10-2)			<ul> <li>Socillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/1 frequency division ratio</li> </ul>	2.7 to 3.6		1.4	2.4	
	IDDHALT(2)		HALT mode     CF1=24MHz external clock     System clock set to CF1 side     Internal low speed and medium speed RC	3.0 to 5.5		2.7	5.3	
			<ul> <li>Internation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/2 frequency division ratio</li> </ul>	3.0 to 3.6		1.6	2.9	
	IDDHALT(3)		HALT mode     FmCF=10MHz ceramic oscillation mode     System clock set to 10MHz side	2.2 to 5.5		2.2	4.3	
		_	<ul> <li>Internal low speed and medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/1 frequency division ratio</li> </ul>	2.2 to 3.6		1.2	2.2	
	IDDHALT(4)		<ul> <li>HALT mode</li> <li>FmCF=4MHz ceramic oscillation mode</li> <li>System clock set to 4MHz side</li> <li>Internal low speed and medium speed RC</li> </ul>	1.8 to 5.5		1.3	3.3	mA
			<ul> <li>Internation stopped and medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/1 frequency division ratio</li> </ul>	1.8 to 3.6		0.56	1.2	
	IDDHALT(5)		<ul> <li>HALT mode</li> <li>CF oscillation low amplifier size selected. (CFLAMP=1)</li> <li>FmCF=4MHz ceramic oscillation mode</li> <li>System clock set to 4MHz side</li> </ul>	2.2 to 5.5		0.74	1.8	
			<ul> <li>System clock set to 4win 2 side</li> <li>Internal low speed and medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/4 frequency division ratio</li> </ul>	2.2 to 3.6		0.34	0.68	
	IDDHALT(6)		HALT mode     FsX'tal=32.768kHz crystal oscillation mode     Internal low speed RC oscillation stopped.	1.8 to 5.5		0.32	0.90	
			<ul> <li>System clock set to internal medium speed RC oscillation</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/2 frequency division ratio</li> </ul>	1.8 to 3.6		0.21	0.44	

Note10-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note10-2: The consumption current values do not include operational current of LVD function if not specified.

Continued on next page.

Parameter	Symbol	Pin/	Conditions			Specif	ication	
Falametei	Symbol	remarks		V <sub>DD</sub> [V]	min	typ	max	unit
HALT mode consumption current (Note 10-1)	IDDHALT(7)	V <sub>DD</sub> 1	<ul> <li>HALT mode</li> <li>FsX'tal=32.768kHz crystal oscillation mode</li> <li>Internal low speed and medium speed RC oscillation stopped.</li> </ul>	1.8 to 5.5		1.3	2.3	mA
(Note 10-2)			<ul> <li>System clock set to 8MHz with frequency variable RC oscillation</li> <li>1/1 frequency division ratio</li> </ul>	1.8 to 3.6		0.91	1.5	
	IDDHALT(8)		<ul> <li>HALT mode</li> <li>External FsX'tal and FmCF oscillation stopped.</li> <li>System clock set to internal low speed RC oscillation.</li> </ul>	1.8 to 5.5		18	68	
			<ul> <li>Internal medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/1 frequency division ratio</li> </ul>	1.8 to 3.6		11	35	
	IDDHALT(9)		<ul> <li>HALT mode</li> <li>External FsX'tal and FmCF oscillation stopped.</li> <li>System clock set to internal low speed RC</li> </ul>	5.0		18	46	
			oscillation. <ul> <li>Internal medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> </ul>	3.3		11	27	
			<ul> <li>1/1 frequency division ratio</li> <li>Ta=-10 to +50°C</li> </ul>	2.5		7.4	19	
	IDDHALT(10)		<ul> <li>HALT mode</li> <li>FsX'tal=32.768kHz crystal oscillation mode</li> <li>System clock set to 32.768kHz side</li> <li>Internal low speed and medium speed RC</li> </ul>	1.8 to 5.5		24	98	
			<ul> <li>Include low speed and median speed no oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> <li>1/2 frequency division ratio</li> </ul>	1.8 to 3.6		8.0	35	
	IDDHALT(11)		<ul> <li>HALT mode</li> <li>FsX'tal=32.768kHz crystal oscillation mode</li> <li>System clock set to 32.768kHz side</li> </ul>	5.0		24	63	_
			<ul> <li>Internal low speed and medium speed RC oscillation stopped.</li> <li>Frequency variable RC oscillation stopped.</li> </ul>	3.3		8.0	23	μA
			<ul> <li>1/2 frequency division ratio</li> <li>Ta=-10 to +50°C</li> </ul>	2.5		3.5	11	
HOLD mode	IDDHOLD(1)		HOLD mode	1.8 to 5.5		0.019	23	
consumption current			• CF1=V <sub>DD</sub> or open (External clock mode)	1.8 to 3.6		0.011	11	
(Note 10-1)	IDDHOLD(2)		<ul> <li>HOLD mode</li> <li>◆ CF1=V<sub>DD</sub> or open (External clock mode)</li> </ul>	5.0		0.019	1.2	
(Note 10-2)			• Ta=-10 to +50°C	3.3		0.011	0.59	
	IDDHOLD(3)		HOLD mode	2.5		0.010	0.30	
	IDDITOLD(0)		• CF1=V <sub>DD</sub> or open (External clock mode)	1.8 to 5.5		2.6	26	
			LVD option selected	1.8 to 3.6		2.0	13	
	IDDHOLD(4)		<ul> <li>HOLD mode</li> <li>◆ CF1=V<sub>DD</sub> or open (External clock mode)</li> </ul>	5.0		2.6	3.8	
			• Ta=-10 to +50°C	3.3		2.0	2.8	
			LVD option selected	2.5		1.7	2.5	
Timer HOLD	IDDHOLD(5)		Timer HOLD mode	1.8 to 5.5		22	84	
mode consumption			FsX'tal=32.768kHz crystal oscillation mode	1.8 to 3.6		6.5	30	
current	IDDHOLD(6)		Timer HOLD mode	5.0		22	53	
(Note 10-1)			<ul> <li>FsX'tal=32.768kHz crystal oscillation mode</li> <li>Ta=-10 to +50°C</li> </ul>	3.3		6.5	16	
(Note 10-2)				2.5		2.7	7.2	

Note10-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note10-2: The consumption current values do not include operational current of LVD function if not specified.

## **F-ROM Programming Characteristics** at $Ta = +10^{\circ}C$ to $+55^{\circ}C$ , $V_{SS}1 = V_{SS}2 = 0V$

Demonster	Ourseland	Dia (Desservice	Que ditiere -		Specification					
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit		
Onboard	IDDFW(1)	V <sub>DD</sub> 1	<ul> <li>Only current of the Flash block.</li> </ul>							
programming				2.2 to 5.5		5	10	mA		
current										
Programming	tFW(1)		Erasing time	0.045.5.5		20	30	ms		
time	tFW(2)		Programming time	2.2 to 5.5		40	60	μs		

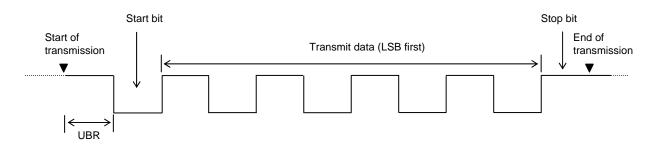
## **UART (Full Duplex) Operating Conditions** at $Ta = -40^{\circ}C$ to $+85^{\circ}C$ , $V_{SS}1 = V_{SS}2 = 0V$

Description	Quercharl	Dia (Darrandua	Qualitiens		Specification					
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit		
Transfer rate	UBR	P20, P21		1.8 to 5.5	16/3		8192/3	tCYC		

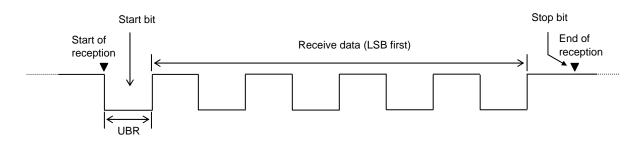
Data length: 7/8/9 bits (LSB first)

Stop bits:1 bit (2-bit in continuous data transmission)Parity bits:None

## Example of Continuous 8-bit Data Transmission Mode Processing (First Transmit Data=55H)



## Example of Continuous 8-bit Data Reception Mode Processing (First Receive Data=55H)



## **Characteristics of a Sample Main System Clock Oscillation Circuit**

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator • CF oscillation normal amplifier size selected (CFLAMP=0)

■MURATA

Nominal	-			Circuit (	Constant		Operating Voltage		lation tion Time	5
Frequency	Туре	Oscillator Name	C1	C2	Rf	Rd	Range	typ	max	Remarks
			[pF]	[pF]	[Ω]	[Ω]	[V]	[ms]	[ms]	
12MHz	SMD	CSTCE12M0G52-R0	(10)	(10)	Open	680	2.6 to 5.5	0.02	0.3	
	SMD	CSTCE10M0G52-R0	(10)	(10)	Open	680	2.1 to 5.5	0.02	0.3	
10MHz		CSTLS10M0G53-B0	(15)	(15)	Open	680	2.4 to 5.5	0.02	0.3	
	LEAD	CSTLS10M0G53095-B0	(15)	(15)	Open	680	2.0 to 5.5	0.01	0.15	
	SMD	CSTCE8M00G52-R0	(10)	(10)	Open	1k	2.1 to 5.5	0.02	0.3	
8MHz		CSTLS8M00G53-B0	(15)	(15)	Open	1k	2.2 to 5.5	0.02	0.3	
	LEAD	CSTLS8M00G53095-B0	(15)	(15)	Open	1k	1.9 to 5.5	0.01	0.15	Internal C1, C2
	CMD	CSTCR6M00G53-R0	(15)	(15)	Open	1.5k	2.0 to 5.5	0.02	0.3	01, 02
	SMD	CSTCR6M00G53093-R0	(15)	(15)	Open	1.5k	1.8 to 5.5	0.01	0.15	
6MHz		CSTLS6M00G53-B0	(15)	(15)	Open	1.5k	2.0 to 5.5	0.02	0.3	
	LEAD	CSTLS6M00G53095-B0	(15)	(15)	Open	1.5k	1.8 to 5.5	0.01	0.15	
4141-	SMD	CSTCR4M00G53-R0	(15)	(15)	Open	1.5k	1.8 to 5.5	0.03	0.45	
4MHz	LEAD	CSTLS4M00G53-B0	(15)	(15)	Open	1.5k	1.8 to 5.5	0.02	0.3	

• CF oscillation low amplifier size selected (CFLAMP=1)

#### ■MURATA

Nominal	-			Circuit (	Constant		Operating Voltage		llation tion Time	
Frequency	Туре	Oscillator Name	C1	C2	Rf	Rd	Range	typ	max	Remarks
			[pF]	[pF]	[Ω]	[Ω]	[V]	[ms]	[ms]	
12MHz	SMD	CSTCE12M0G52-R0	(10)	(10)	Open	470	3.9 to 5.5	0.03	0.45	
	SMD	CSTCE10M0G52-R0	(10)	(10)	Open	470	2.9 to 5.5	0.03	0.45	
10MHz		CSTLS10M0G53-B0	(15)	(15)	Open	470	3.6 to 5.5	0.03	0.45	
	LEAD	CSTLS10M0G53095-B0	(15)	(15)	Open	470	2.7 to 5.5	0.02	0.3	
	SMD	CSTCE8M00G52-R0	(10)	(10)	Open	680	2.7 to 5.5	0.03	0.45	
8MHz	1540	CSTLS8M00G53-B0	(15)	(15)	Open	680	3.0 to 5.5	0.03	0.45	
	LEAD	CSTLS8M00G53095-B0	(15)	(15)	Open	680	2.5 to 5.5	0.01	0.15	
	0145	CSTCR6M00G53-R0	(15)	(15)	Open	1k	2.6 to 5.5	0.03	0.45	Internal C1, C2
01411	SMD	CSTCR6M00G53095-R0	(15)	(15)	Open	1k	2.2 to 5.5	0.02	0.3	01,02
6MHz	1540	CSTLS6M00G53-B0	(15)	(15)	Open	1k	2.7 to 5.5	0.03	0.45	
	LEAD	CSTLS6M00G53095-B0	(15)	(15)	Open	1k	2.2 to 5.5	0.01	0.15	
	0145	CSTCR4M00G53-R0	(15)	(15)	Open	1k	2.1 to 5.5	0.04	0.6	
	SMD	CSTCR4M00G53095-R0	(15)	(15)	Open	1k	1.8 to 5.5	0.02	0.3	
4MHz	CSTLS4M00G53-B0	(15)	(15)	Open	1k	2.1 to 5.5	0.02	0.3		
	LEAD	CSTLS4M00G53095-B0	(15)	(15)	Open	1k	1.8 to 5.5	0.01	0.15	

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in follwing cases (see Figure 3).

- The time interval that is required for the oscillation to get stabilized after the instruction for starting the mainclock oscillation circuit is executed.
- The time interval that is required for the oscillation to get stabilized after the HOLD mode is reset and oscillation is started.
- The time interval that is required for the oscillation to get stabilized after the X'tal Hold mode, under the state which the main clock oscillation is enabled, is reset and oscillation is started.

## Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator ■EPSON TOYOCOM

Nominal	Tura	Oscillator		Circuit C	Constant		Operating Voltage		lation tion Time	Demeric
Frequency	Туре	Name	C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]	Range [V]	typ [s]	max [s]	Remarks
32.768kHz	SMD	MC-306	9	9	Open	330k	1.8 to 5.5	1.4	4.0	Applicable CL value = 7.0pF

#### SEIKO INSTRUMENTS

Nominal	Turne	Oscillator		Circuit C	Constant		Operating Voltage		lation tion Time	Demeric
Frequency	Туре	Name	C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]	Range [V]	typ [s]	max [s]	Remarks
32.768kHz	SMD	SSP-T7-F	18	22	Open	330k	1.8 to 5.5	0.75	2.0	Applicable CL value = 12.5pF

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after  $V_{DD}$  goes above the operating voltage lower limit (see Figure 3).

- The time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed.
- The time interval that is required for the oscillation to get stabilized after the Hold mode, under the state which the subclock oscillation is enabled, is reset and oscillation is started.

(Notes on the implementation of the oscillator circuit)

- Oscillation is influenced by the circuit pattern layout of printed circuit board. Place the oscillation-related components as close to the CPU chip and to each other as possible with the shortest possible pattern length.
- Keep the signal lines whose state changes suddenly or in which large current flows as far away from the oscillator circuit as possible and make sure that they do not cross one another.
- Be sure to insert a current limiting resistor (Rd) so that the oscillation amplitude never exceeds the input voltage level that is specified as the absolute maximum rating.
- The oscillator circuit constants shown above are sample characteristic values that are measured using the Our designated oscillation evaluation board. Since the accuracy of the oscillation frequency and other characteristics vary according to the board on which the IC is installed, it is recommended that the user consult the resonator vendor for oscillation evaluation of the IC on a user's production board when using the IC for applications that require high oscillation accuracy. For further information, contact your resonator vendor or Our company sales representative serving your locality.
- It must be noted, when replacing the flash ROM version of a microcontroller with a mask ROM version, that their operating voltage ranges may differ even when the oscillation constant of the external oscillator is the same.

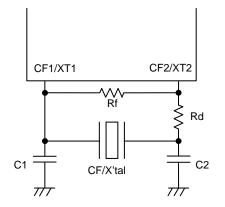


Figure 1 CF and XT Oscillator Circuit

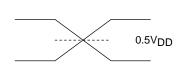
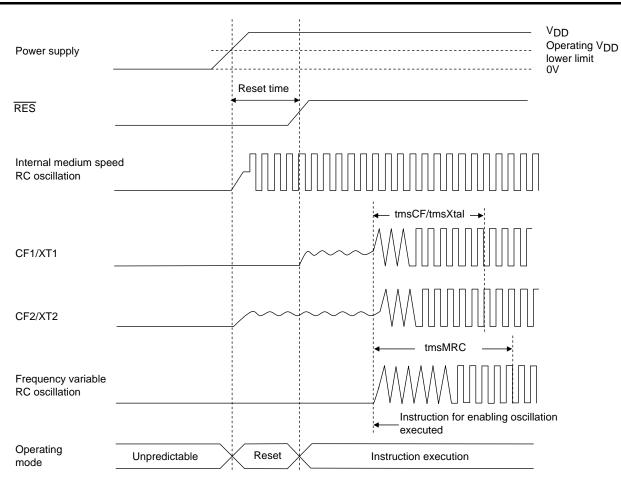
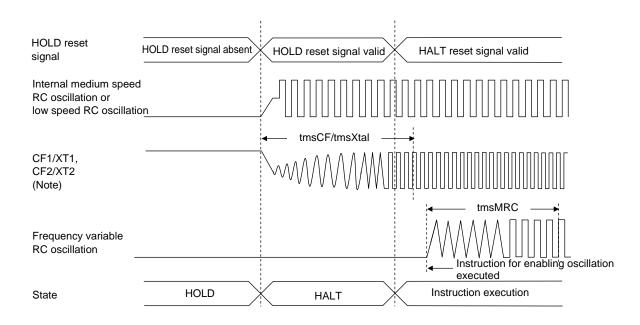


Figure 2 AC Timing Measurement Point



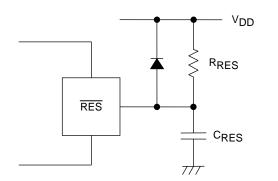
#### Reset Time and Oscillation Stabilization Time



#### HOLD Reset Signal and Oscillation Stabilization Time

Note: External oscillation circuit is selected.

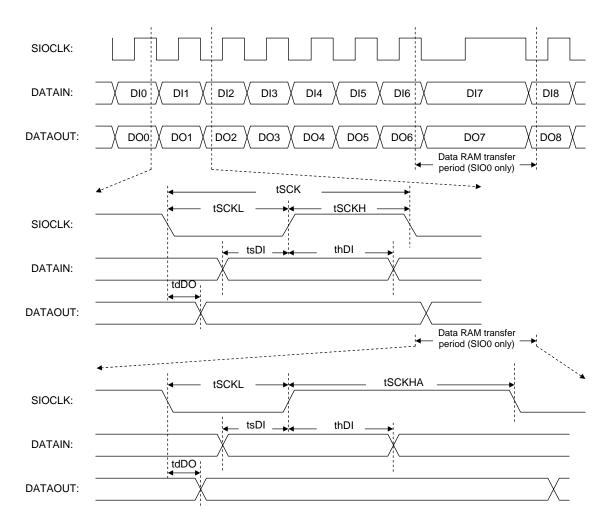
Figure 3 Oscillation Stabilization Times



Note:

External circuits for reset may vary depending on the usage of POR and LVD. Please refer to the user's manual for more information.





#### Figure 5 Serial I/O Output Waveforms

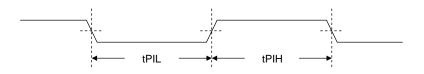


Figure 6 Pulse Input Timing Signal Waveform

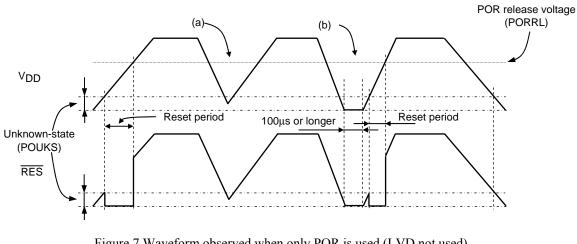


Figure 7 Waveform observed when only POR is used (LVD not used) (RESET pin: Pull-up resistor R<sub>RES</sub> only)

- The POR function generates a reset only when power is turned on starting at the VSS level.
- No stable reset will be generated if power is turned on again when the power level does not go down to the VSS level as shown in (a). If such a case is anticipated, use the LVD function together with the POR function or implement an external reset circuit.
- A reset is generated only when the power level goes down to the VSS level as shown in (b) and power is turned on again after this condition continues for 100µs or longer.

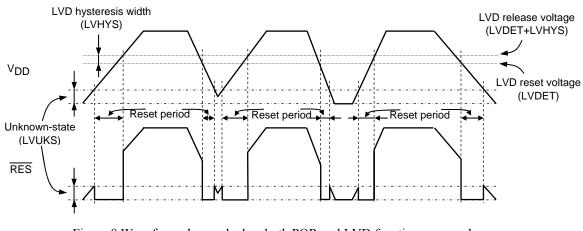


Figure 8 Waveform observed when both POR and LVD functions are used (RESET pin: Pull-up resistor R<sub>RES</sub> only)

- Resets are generated both when power is turned on and when the power level lowers.
- A hysteresis width (LVHYS) is provided to prevent the repetitions of reset release and entry cycles near the detection level.

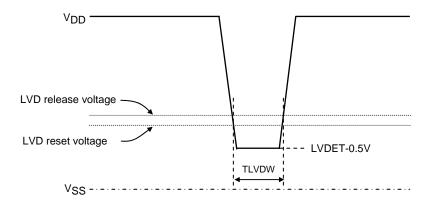


Figure 9 Low voltage detection minimum width (Example of momentary power loss/Voltage variation waveform)

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